

Title (en)

METHOD AND DEVICE FOR ISOLATING PLATE-LIKE SUBSTRATES

Title (de)

VERFAHREN UND EINRICHTUNG ZUM VEREINZELN VON SCHEIBENFÖRMIGEN SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF POUR SEPARER DES SUBSTRATS EN FORME DE TRANCHE

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Application

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Abstract (en)

[origin: WO0128745A1] The invention relates to a method for isolating and detaching thin, fragile, plate-like substrates (11). Said plate-like substrates (11) are cut from a substrate block (13), which is preferably mounted on a baseplate (12) by means of adhesive, are gripped at evenly distributed points on the free outer surface thereof (16) and are displaced in an oscillating manner, such that the plate-like substrates (11) are automatically and individually removed free of damage from the sawn substrate block and from the layer of adhesive.

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